

Product Summary

BV_{DSS}	R_{DS(ON)} MAX	I_D MAX T_C = +25°C
700V	1.0Ω @ V _{GS} = 10V	6A

Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

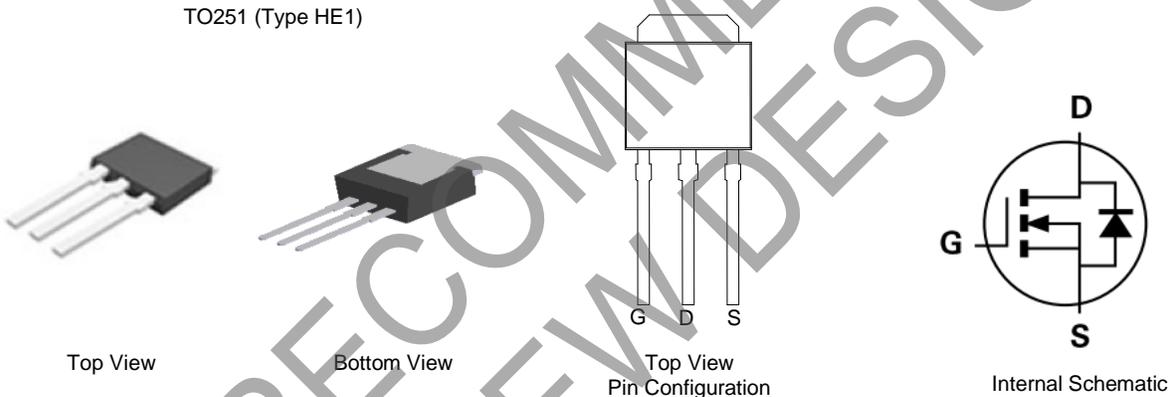
Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Adaptor
- LCD & PDP TV
- Lighting

Mechanical Data

- Case: TO251 (Type HE1)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 **(E3)**
- Weight: 0.33 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMJ70H1D0SV3	TO251 (Type HE1)	75pieces / Tube

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

TO251 (Type HE1)



D = Manufacturer's Marking
6N70SV = Product Type Marking Code
YYWW = Date Code Marking
YY or **YY** = Last Two Digits of Year (ex: 18 = 2018)
WW or **WW** = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	700	V
Gate-Source Voltage	V _{GSS}	±30	V
Continuous Drain Current (Note 5) V _{GS} = 10V	I _D	T _C = +25°C	6.0
		T _C = +100°C	4.5
Maximum Body Diode Forward Current (Note 6)	I _S	3.5	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	8.0	A
Avalanche Current (Note 7)	I _{AS}	0.5	A
Avalanche Energy (Note 7)	E _{AS}	7.5	mJ
Peak Diode Recovery dv/dt (Note 7)	dv/dt	5	V/ns

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	T _C = +25°C	104
		T _C = +100°C	42
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	74	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	1.2	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	700	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	µA	V _{DS} = 700V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	100	nA	V _{GS} = ±30V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	2	3.4	4	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	0.9	1.0	Ω	V _{GS} = 10V, I _D = 1.5A
Diode Forward Voltage	V _{SD}	—	0.85	1.3	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{ISS}	—	420	—	pF	V _{DS} = 50V, f = 1MHz, V _{GS} = 0V
Output Capacitance	C _{OSS}	—	161	—		
Reverse Transfer Capacitance	C _{RSS}	—	4.3	—		
Gate Resistance	R _g	—	1.8	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	—	12.8	—	nC	V _{DD} = 560V, I _D = 5A, V _{GS} = 10V
Gate-Source Charge	Q _{gs}	—	1.8	—		
Gate-Drain Charge	Q _{gd}	—	6.2	—		
Turn-On Delay Time	t _{D(ON)}	—	8	—	ns	V _{DD} = 350V, V _{GS} = 10V, R _g = 4.7Ω, I _D = 5A
Turn-On Rise Time	t _r	—	14	—		
Turn-Off Delay Time	t _{D(OFF)}	—	23	—		
Turn-Off Fall Time	t _f	—	3	—		
Body Diode Reverse Recovery Time	t _{RR}	—	217	—	ns	I _S = 5A, di/dt = 100A/µs
Body Diode Reverse Recovery Time (T _J = +150°C)	t _{RR}	—	292	—	ns	
Body Diode Reverse Recovery Charge	Q _{RR}	—	1.9	—	µC	
Body Diode Reverse Recovery Charge (T _J = +150°C)	Q _{RR}	—	2.8	—	µC	

- Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
 6. Device mounted on FR-4 substrate PC board, 2oz. copper, with minimum recommended pad layout.
 7. Guaranteed by design. Not subject to production testing.
 8. Short duration pulse test used to minimize self-heating effect.

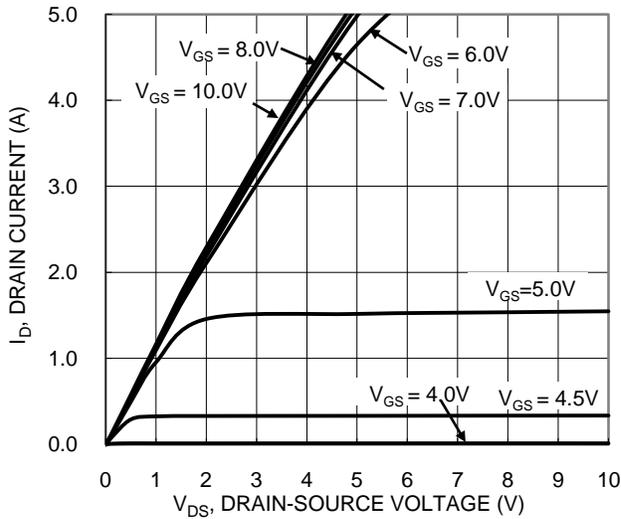


Figure 1. Typical Output Characteristic

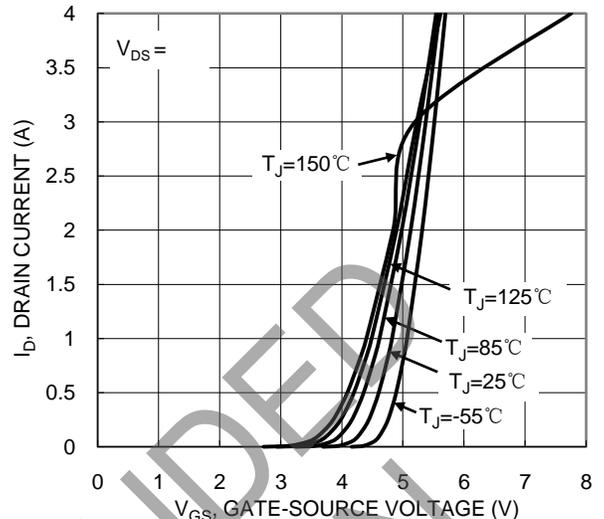


Figure 2. Typical Transfer Characteristic

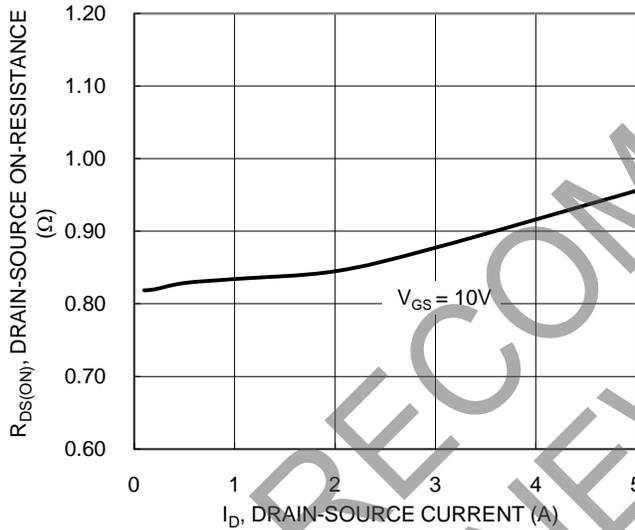


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

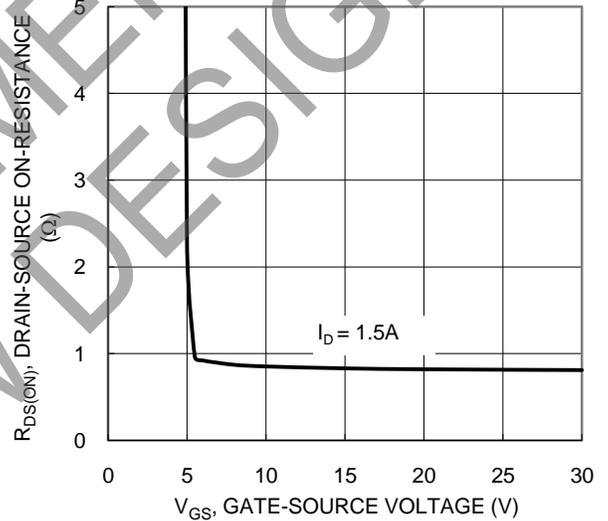


Figure 4. Typical Transfer Characteristic

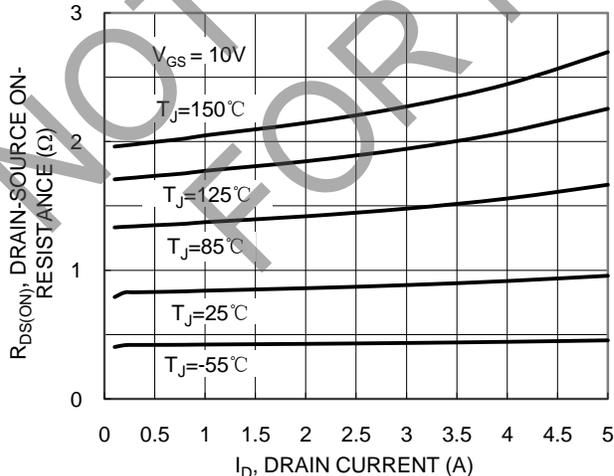


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

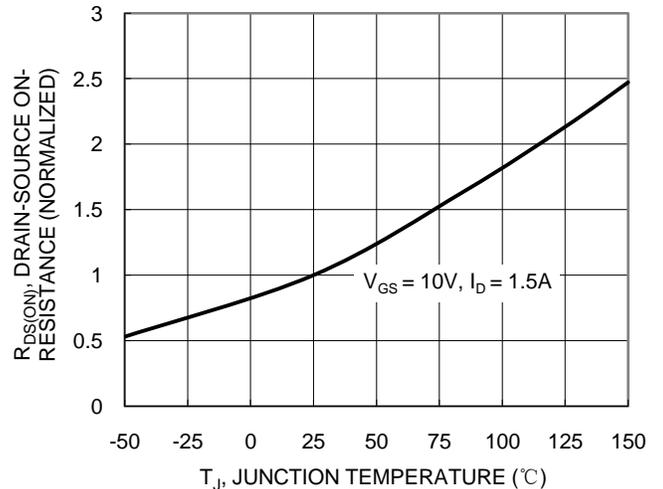


Figure 6. On-Resistance Variation with Temperature

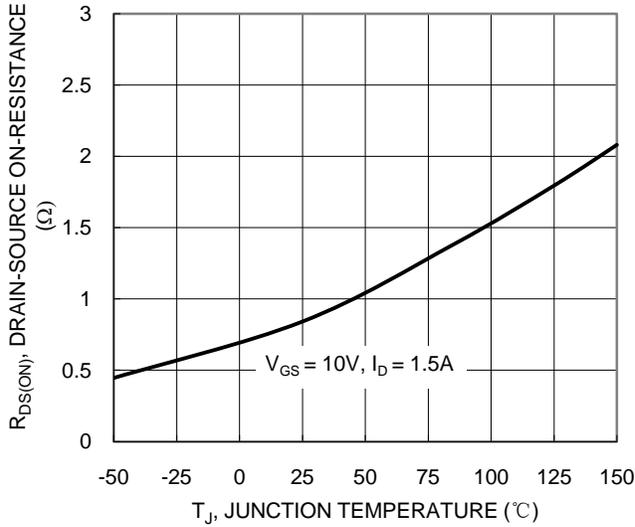


Figure 7. On-Resistance Variation with Temperature

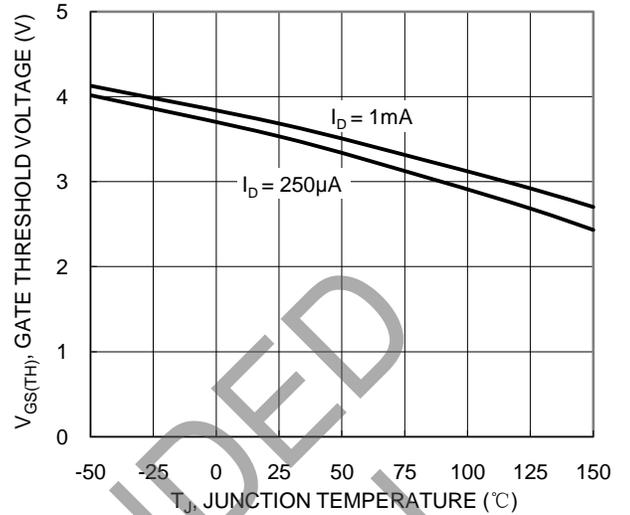


Figure 8. Gate Threshold Variation vs. Junction Temperature

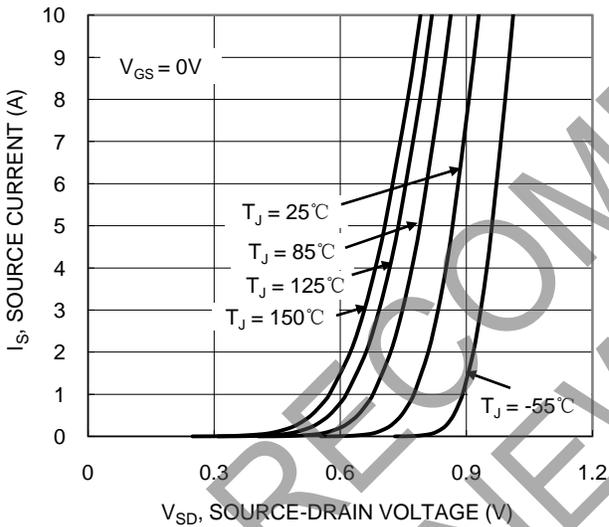


Figure 9. Diode Forward Voltage vs. Current

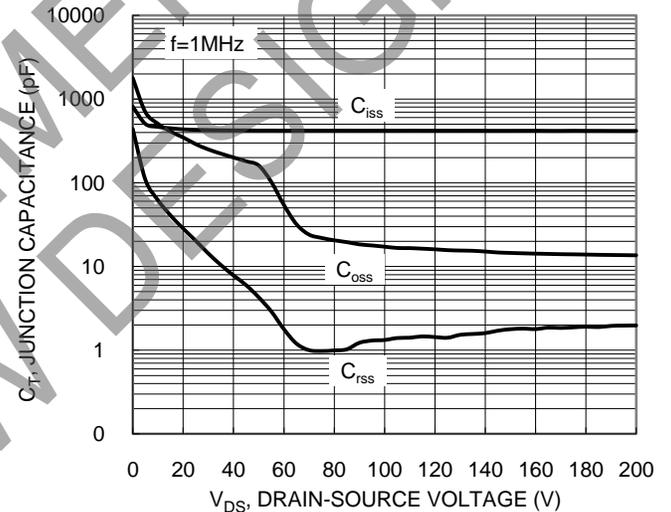


Figure 10. Typical Junction Capacitance

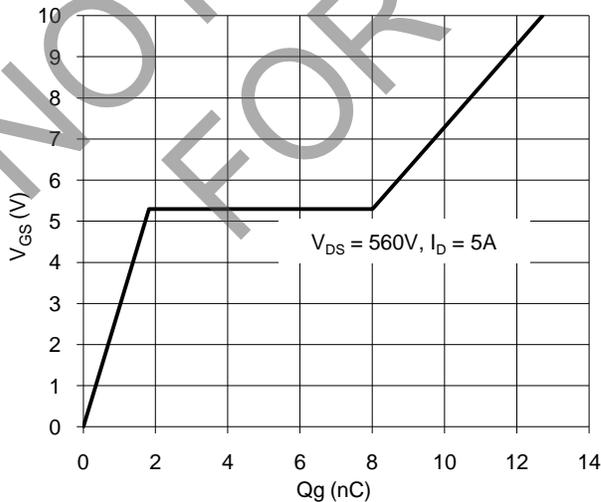


Figure 11. Gate Charge

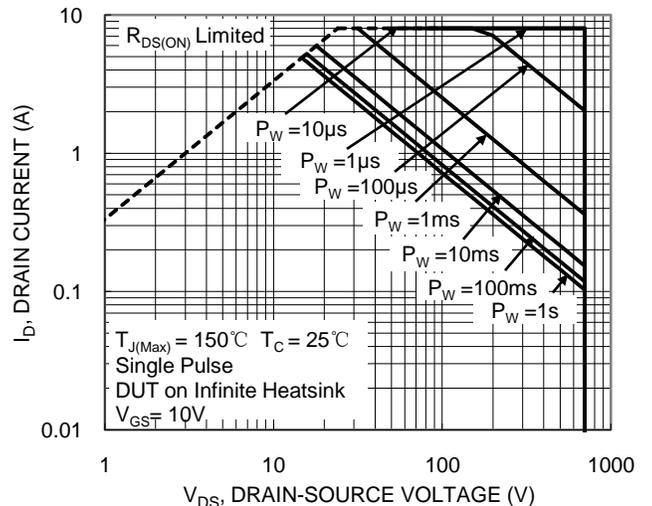


Figure 12. SOA, Safe Operation Area

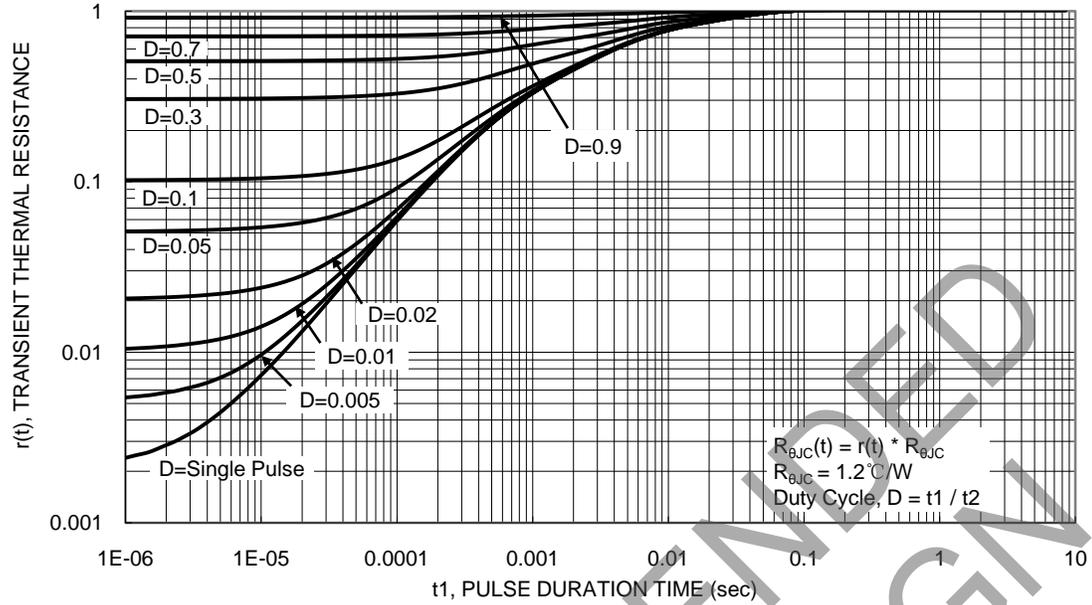
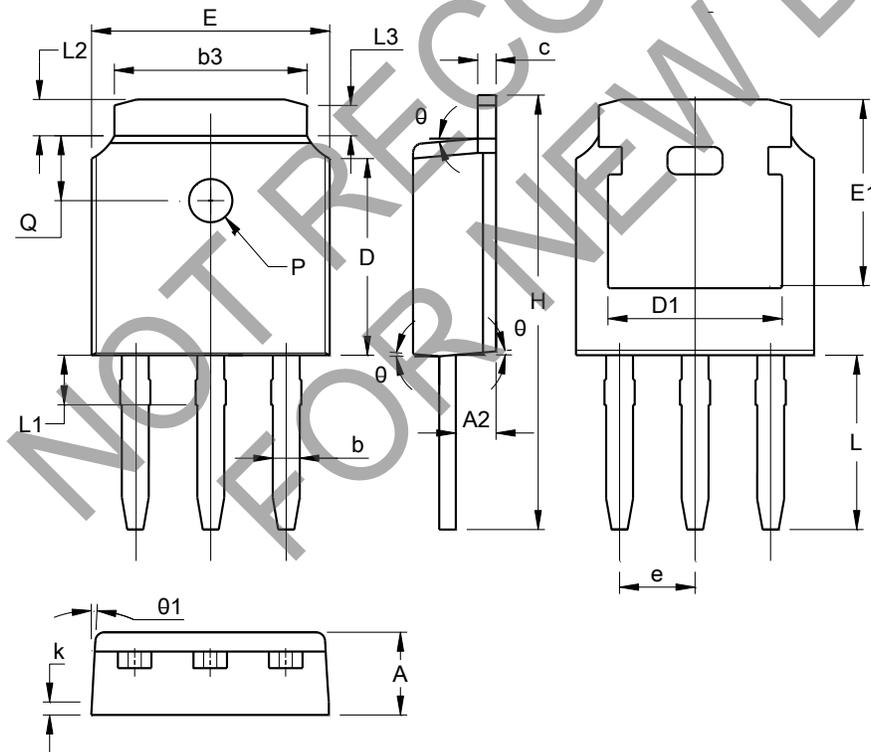


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO251 (Type HE1)



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Dim	Min	Max	Typ
A	2.20	2.40	2.30
A2	0.97	1.17	1.07
b	0.68	0.90	0.78
b3	5.20	5.50	5.33
c	0.43	0.63	0.53
D	5.98	6.22	6.10
D1	5.30 REF		
e	2.286 BSC		
E	6.40	6.80	6.60
E1	4.63	5.03	4.83
H	10.00	11.44	11.22
k	0.40REF		
L	3.90	4.30	4.10
L1	0.85	1.25	1.05
L2	0.88	1.28	1.02
L3	0.75 REF		
Q	1.65	1.95	1.80
PØ	1.20		
θ	5°	9°	7°
θ1	5°	9°	7°
All Dimensions in mm			

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